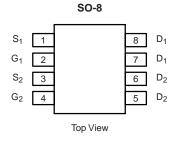


DMP3028LSD-13-F-VB Datasheet Dual P-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|------------------------------------|------------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) ^{d, e} | Q _g (Typ.) | | | |
| - 30 | 0.021 at V _{GS} = - 10 V | - 8.0 | 15 nC | | | |
| - 30 | 0.028 at V _{GS} = - 4.5 V | - 7.0 | 15110 | | | |



FEATURES

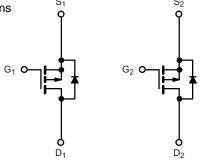
- · Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

Pb-free

RoHS

APPLICATIONS

- · Load Switches
 - Notebook PCs
 - Desktop PCs
 - Game Stations



P-Channel MOSFET

P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS | $\Gamma_A = 25 ^{\circ}\text{C}$, unless other | erwise noted | | |
|---|--|-------------------|-----------------------|----|
| Parameter | Symbol | Limit | Unit | |
| Drain-Source Voltage | V _{DS} | - 30 | V | |
| Gate-Source Voltage | V _{GS} | ± 20 | V | |
| | T _C = 25 °C | | - 9.5 ^e | |
| Continuous Drain Current (T _{.1} = 150 °C) | T _C = 70 °C | | - 8.0 ^e | |
| Continuous Diain Current (1) = 130 °C) | T _A = 25 °C | l _D | - 8.3 ^{a, b} | |
| | T _A = 70 °C | | - 7.9 ^{a, b} | Α |
| Pulsed Drain Current | I _{DM} | - 32 ^e | ^ | |
| 0 1 0 0 0 1 | T _C = 25 °C | L | - 4.1 | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | I _S | - 2.0 ^{a, b} | |
| Avalanche Current | L = 0.1 mH | I _{AS} | - 20 | |
| Single-Pulse Avalanche Energy | L = U.1 IIII | E _{AS} | 20 | mJ |
| | T _C = 25 °C | | 5.0 | |
| Maximum Dawar Dissination | T _C = 70 °C | P_{D} | 3.2 | W |
| Maximum Power Dissipation | T _A = 25 °C | T FD | 2.5 ^{a, b} | VV |
| | T _A = 70 °C | | 1.6 ^{a, b} | |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | - 55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---|--------------|-------------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^{a, c} | t ≤ 10 s | R _{thJA} | 38 | 50 | °C/W | |
| Maximum Junction-to-Foot | Steady State | R_{thJF} | 20 | 25 | C/VV | |

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on $T_C = 25$ °C.
- e. Limited by package.



| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|--|--|-------|--------|-------|--------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$ | - 30 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = - 250 μA | | - 31 | | m\//9C | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | 4.5 | | mV/°C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | - 1.0 | | - 3.0 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| Zoro Coto Voltago Drain Current | lana | V _{DS} = - 30 V, V _{GS} = 0 V | | | - 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C | | | - 5 | μΑ | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$ | - 30 | | | Α | |
| Durin Course Co Otata Basista and | D | V _{GS} = - 10 V, I _D = - 7.3 A | | 0.021 | | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 4.5 V, I _D = - 6.2 A | | 0.028 | | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 10 V, I _D = - 9.1 A | | 23 | | S | |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | | 1350 | | | |
| Output Capacitance | C _{oss} | $V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 215 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 185 | | | |
| Total Gate Charge | Q_g $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -9.1 \text{ A}$ | $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -9.1 \text{ A}$ | | 32 | 50 | | |
| | | | 15 | 25 | -0 | | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -9.1 \text{ A}$ | | 4 | | nC | |
| Gate-Drain Charge | Q _{gd} | | | 7.5 | | | |
| Gate Resistance | R _g | f = 1 MHz | | 5.8 | | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 10 | 15 | | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$ | | 8 | 15 | | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$ | | 45 | 70 | | |
| Fall Time | t _f | | | 12 | 25 | | |
| Turn-On Delay Time | t _{d(on)} | | | 42 | 70 | ns | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$ | | 35 | 60 | | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω | | 40 | 70 | | |
| Fall Time | t _f | | | 16 | 30 | | |
| Drain-Source Body Diode Characterist | ics | | | | | • | |
| Continous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 4.1 | ^ | |
| Pulse Diode Forward Current | I _{SM} | | | | - 32 | Α | |
| Body Diode Voltage | V _{SD} | I _S = -2 A, V _{GS} = 0 V | | - 0.75 | - 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 34 | 60 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 22 | 40 | nC | |
| Reverse Recovery Fall Time | t _a | $I_F = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | | 11 | | 1 | |
| Reverse Recovery Rise Time | t _b | | | 23 | | ns | |

Notes:

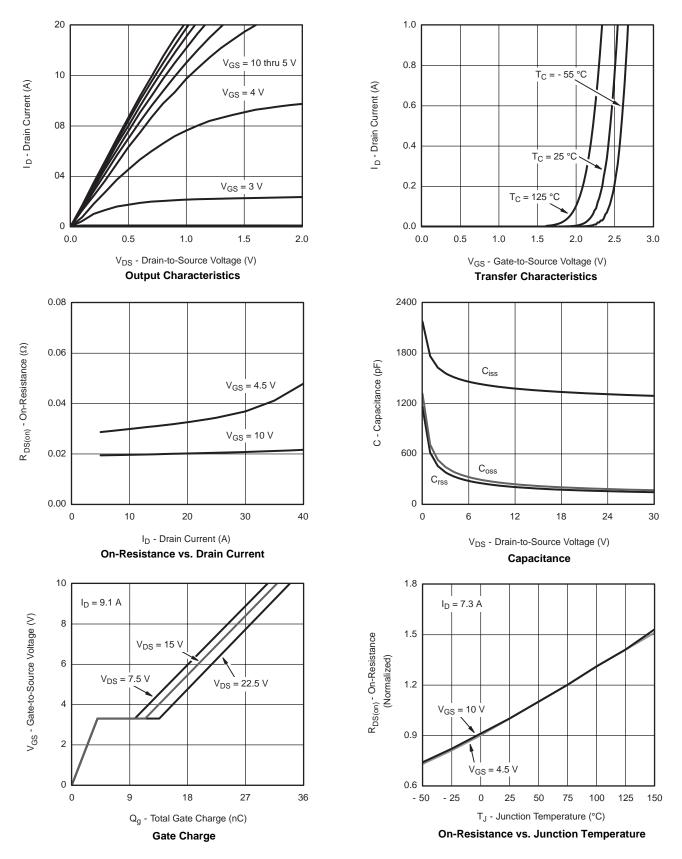
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



0.6

0.4

0.2

0.0

- 50

- 25

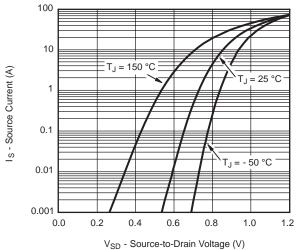
0

25

V_{GS(th)} Variance (V)

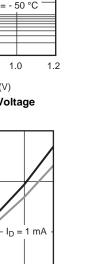


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Source-Drain Diode Forward Voltage

 $I_D = 250 \ \mu A$



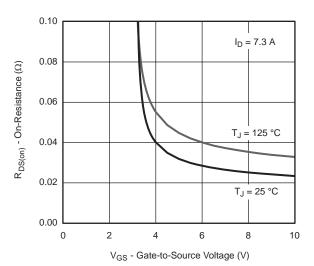
T_J - Temperature (°C) Threshold Voltage

50

75

100

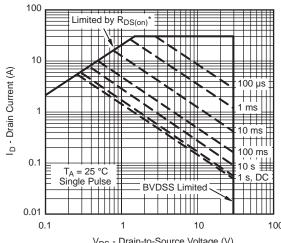
125 150



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



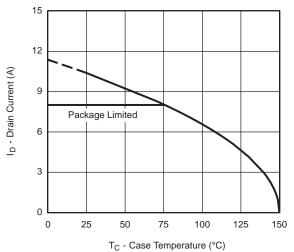
V_{DS} - Drain-to-Source Voltage (V)

Safe Operating Area

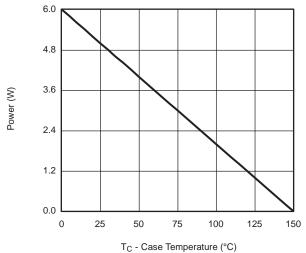
^{*} V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

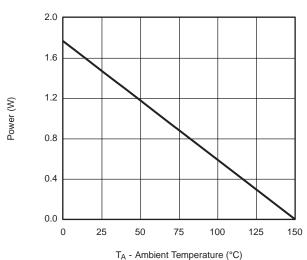


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted









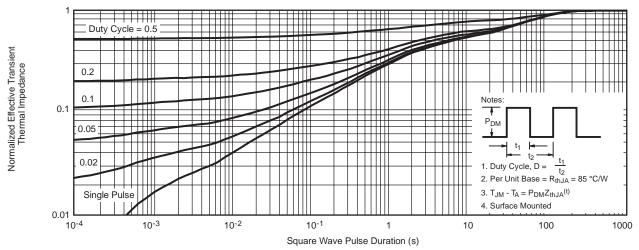
Power, Junction-to-Foot

Power Derating, Junction-to-Ambient

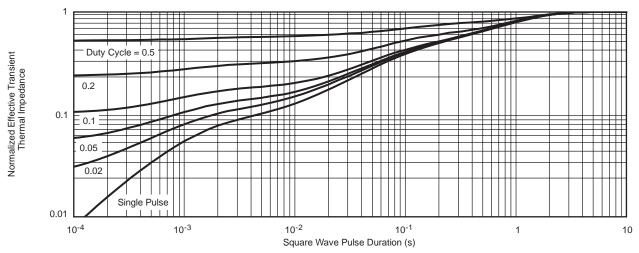
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



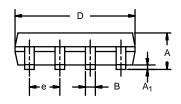
Normalized Thermal Transient Impedance, Junction-to-Foot



7

SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







| | MILLIM | IETERS | INCHES | | | |
|------------------------------|--------|--------|--------|-----------|--|--|
| DIM | Min | Max | Min | Max | | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | | |
| E | 3.80 | 4.00 | 0.150 | 0.157 | | |
| е | 1.27 | BSC | 0.050 | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | | |
| q | 0° | 8° | 0° | 8° | | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | | |
| ECN: C-06527-Pey 11-Sep-06 | | | | | | |

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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